

Title (en)
METHOD FOR PRODUCING AN ELECTRICAL THROUGH-PLATING

Title (de)
VERFAHREN ZUR HERSTELLUNG EINER ELEKTRISCHEN DURCHKONTAKTIERUNG

Title (fr)
PROCÉDÉ POUR LA PRODUCTION D'UN TROU D'INTERCONNEXION ÉLECTRIQUE

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Application
EP 12709304 A 20120307

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Abstract (en)
[origin: WO2012126725A1] The invention relates to an integrated circuit (1), comprising a substrate (10) having a first surface (11) and an opposing second surface (12), wherein a functionalized region (13) is formed at least on the first surface (11) and wherein at least one electrical through-plating (40) is provided as a through-hole (42) which is continuously filled with an electrically conductive material (44) and which runs from the first surface (11) to the second surface (12) through the substrate (10). In order to ensure that the through-plating (40) can be reliably produced and is provided in a space-saving manner, the through-hole (42) has at least one gradation (46) on which a transition occurs from a smaller hole cross-section (d1) on the side of the first surface (11) to a larger hole cross-section (d2) on the side of the second surface (12).

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